



Material Content Data Sheet



Sales Product Name				IPS80R2K0P7		Issued		24. January 2018	
MA#				MA002116610					
Package				PG-TO251-3-342		Weight*		317.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.085	0.34	0.34	3422	3422	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	iron	7439-89-6	0.147	0.05		464		
	non noble metal	copper	7440-50-8	147.096	46.37	46.43	463664	464267	
	non noble metal	aluminium	7429-90-5	0.149	0.05	0.05	469	469	
wire	non noble metal	aluminium	7429-90-5	0.149	0.05	0.05	469	469	
encapsulation	organic material	carbon black	1333-86-4	1.429	0.45		4503		
	plastics	epoxy resin	-	25.000	7.88		78804		
	inorganic material	silicondioxide	60676-86-0	116.430	36.70	45.03	367000	450307	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11789	11789	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4478	4489	
solder	non noble metal	tin	7440-31-5	0.030	0.01		95		
	noble metal	silver	7440-22-4	0.038	0.01		118		
	non noble metal	lead	7439-92-1	1.433	0.45	0.47	4516	4729	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60449	60528	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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